

Product / Process Change Notice

Parts Affected:

Chip process CPZ18, Zener Diode discrete semiconductors, wafers, and die in chip form.

Extent of Change:

An overall reduction of the die area and die thickness.

The CPZ18 chip process currently measures 13.8 x 13.8 x 7.5 mils and is being replaced by the CPZ28X chip processes which measures 13 x 13 x 5.5 mils.

Reason for Change:

To accommodate assemblies of extremely small, low profile, surface mount, epoxy molded packages.

Effect of Change:

This change does not affect the electrical characteristics of any device.

Qualification:

Standard evaluation and qualifications completed resulting in no electrical rejects.

Effective Date of Change:

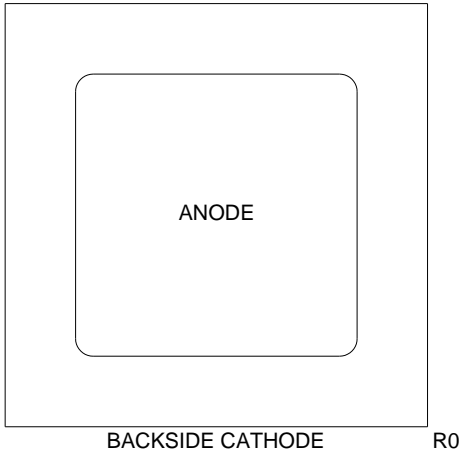
Existing inventory will be shipped until depleted.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

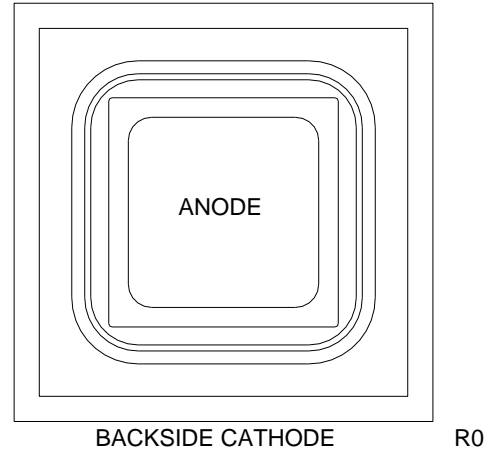
Figures:

Figure 1: CPZ18 Chip Geometry



Die Size:	13.8 x 13.8 mils
Die Thickness:	7.5 mils
Bond Pad Area (Anode):	7.5 x 7.5 mils
Topside Metal:	Al (13,000Å)
Backside Metal:	Au (14,000Å)

Figure 2: CPZ28X Chip Geometry



Die Size:	13 x 13 mils
Die Thickness:	5.5 mils
Bond Pad Area (Anode):	7 x 7 mils
Topside Metal:	Ti/Al (13,000Å)
Backside Metal:	Au/As (13,000Å)

Part Numbers Affected:

CPZ18-CMPZ5221B-CT thru CPZ18-CMPZ5234B-CT
CPZ18-CMPZ5221B-WN thru CPZ18-CMPZ5234B-WN
CPZ18-BZX84C2V4-CT thru CPZ18-BZX84C6V2-CT
CPZ18-BZX84C2V4-WN thru CPZ18-BZX84C6V2-WN
BZX84C2V4 thru BZX84C6V2
CMPZ5221B thru CMPZ5234B
CMDZ5221B thru CMDZ5234B
CMSZ5221B thru CMSZ5234B
CMHZ5221B thru CMHZ5234B
CMKZ5221B thru CMKZ5234B
CMLZDA2V4 thru CMLZDA6V2
CMPZDA2V4 thru CMPZDA6V2
CMSZDA2V4 thru CMSZDA6V2
CMDZ2V4 thru CMDZ6V2
CMDZ1L8 thru CMDZ6L2
CMOZ2V4 thru CMOZ6V2
CMOZ1L8 thru CMOZ6L2
CMXZ2V4TO thru CMXZ6V2TO
CMPZ4614 thru CMPZ4627
CMHZ4614 thru CMHZ4627
CMPZ4678 thru CMPZ4691
CMHZ4678 thru CMHZ4691